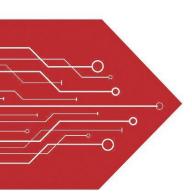
MSKSEMI















ESD

TVS

TSS

MOV

GDT

PLED

Broduct data speet





Features

- 150 Watts peak pulse power (tp = $8/20\mu s$)
- Transient protection for high speed data lines to IEC 61000-4-2 (ESD) ±15kV (air), ±8kV (contact) IEC 61000-4-4 (EFT) 40A (5/50ns)
- Working voltages : 5V
- Protects Two Power or I/O Port
- Low operating and clamping voltages
- Solid-state silicon avalanche technology

Applications

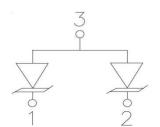
- Notebooks, Desktops, Servers and Video Graphics Cards
- **USB Power & Data Line Protection**
- Monitors and Flat Panel Displays
- I²C Bus Protection
- Portable Instrumentation
- Set Top Box

Electrical Characteristics@ Ta=25°C unless otherwise

	VRWM@IR		VBR@ImA	Vc@1	Vc@IPP		CJ
P/N	V	μΑ	V	V	V	Α	pF
		MAX	MIN	MAX	MAX		MAX
RCLAMP0502BATCT-MS	5	1	6	9.8	15	3	0.9

Maximum Rating @ Ta=25°C unless otherwise specified

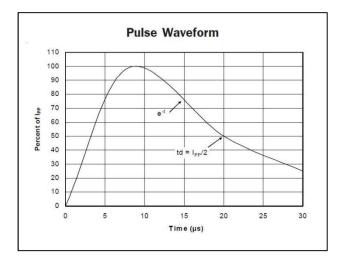
Symbol	Parameter	Ratings	Units
P _{PK}	Peak Pulse Power (tp = 8/20μs)	150	Watts
TL	Lead Soldering Temperature	260(10sec.)	$^{\circ}$
TJ	Operating Temperature	-55 to +125	$^{\circ}$
T _{STG}	Storage Temperature	-55 to +150	$^{\circ}$

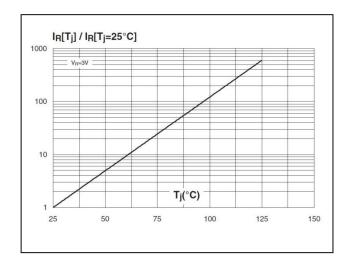


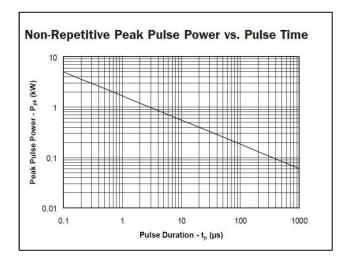
SOT-523

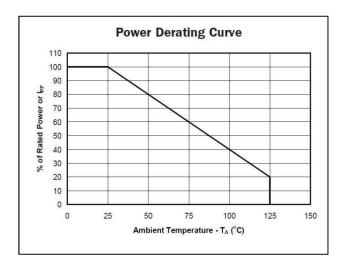


Typical Characteristics@ Ta=25°C unless otherwise specified

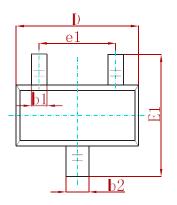


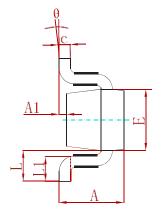


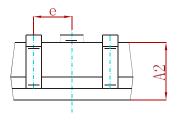






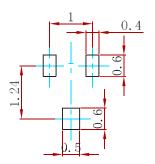






Cumbal	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	0.700	0.900	0.028	0.035	
A1	0.000	0.100	0.000	0.004	
A2	0.700	0.800	0.028	0.031	
b1	0.150	0.250	0.006	0.010	
b2	0.250	0.350	0.010	0.014	
С	0.100	0.200	0.004	0.008	
D	1.500	1.700	0.059	0.067	
E	0.700	0.900	0.028	0.035	
E1	1.450	1.750	0.057	0.069	
е	0.500 TYP.		0.020 TYP.		
e1	0.900	1.100	0.035	0.043	
L	0.400	REF.	0.016 REF.		
L1	0.260	0.460	0.010	0.018	
0	0°	8°	0°	8°	

Suggested Pad Layout



Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:±0.05mm.
- 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
RCLAMP0502BATCT-MS	SOT-523	3000



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